

Title (en)
SEALING SHEET

Title (de)
DICHTUNGSFOLIE

Title (fr)
FEUILLE D'ÉTANCHÉITÉ

Publication
EP 3190612 A1 20170712 (EN)

Application
EP 15837854 A 20150821

Priority
• JP 2014179311 A 20140903
• JP 2015073544 W 20150821

Abstract (en)
Provided is a sealing sheet capable of preventing void and filler segregation from occurring when forming a sealing body in which semiconductor chips are buried in the sealing sheet. The sealing sheet has a viscosity within the range of 1 Pa·s to 50000 Pa·s at 90°C.

IPC 8 full level
H01L 23/29 (2006.01); **C09J 7/22** (2018.01); **C09J 7/30** (2018.01); **H01L 21/56** (2006.01); **H01L 23/31** (2006.01)

CPC (source: EP US)
C09J 7/22 (2017.12 - EP US); **C09J 7/30** (2017.12 - EP US); **H01L 21/56** (2013.01 - EP US); **H01L 23/10** (2013.01 - US); **H01L 23/29** (2013.01 - EP US); **H01L 23/31** (2013.01 - EP US); **H01L 23/3142** (2013.01 - US); **H01L 24/19** (2013.01 - EP US); **H01L 24/20** (2013.01 - EP US); **H01L 24/96** (2013.01 - EP US); **H01L 24/97** (2013.01 - EP US); **H01L 21/561** (2013.01 - EP US); **H01L 21/568** (2013.01 - EP US); **H01L 2224/04105** (2013.01 - EP US); **H01L 2224/12105** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - US); **H01L 2924/18162** (2013.01 - EP US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
EP 3190612 A1 20170712; EP 3190612 A4 20170927; CN 106796922 A 20170531; JP 2016054211 A 20160414; JP 6302801 B2 20180328; SG 11201701446Y A 20170330; TW 201612283 A 20160401; US 10074582 B2 20180911; US 2017287800 A1 20171005; WO 2016035577 A1 20160310

DOCDB simple family (application)
EP 15837854 A 20150821; CN 201580047044 A 20150821; JP 2014179311 A 20140903; JP 2015073544 W 20150821; SG 11201701446Y A 20150821; TW 104128692 A 20150831; US 201515507923 A 20150821